Ordering number : ENN6935

MOSFET : N-Channel Silicon MOSFET
SBD : Schottky Barrier Diode

CPH5803

DC / DC Converter Applications

Features

- Composite type with an N-Channel Sillicon MOSFET (MCH3405) and a Schottky Barrier Diode (SBS004M) contained in one package facilitating high-density mounting.

[MOSFET]

- Low ON-resistance.
- Ultrahigh-speed switching.
- 1.8V drive.

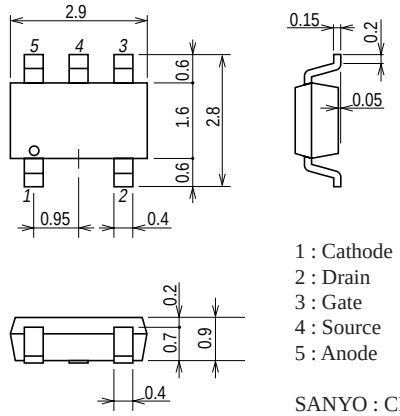
[SBD]

- Short reverse recovery time.
- Low forward voltage.

Package Dimensions

unit : mm
2171

[CPH5803]



1 : Cathode
2 : Drain
3 : Gate
4 : Source
5 : Anode

SANYO : CPH5

Specifications

Absolute Maximum Ratings at Ta=25°C

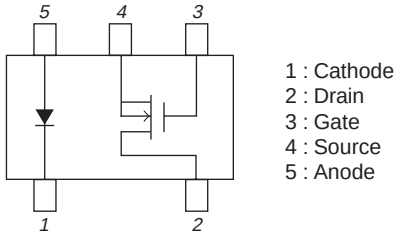
Parameter	Symbol	Conditions	Ratings	Unit
[MOSFET]				
Drain-to-Source Voltage	V_{DSS}		20	V
Gate-to-Source Voltage	V_{GSS}		±10	V
Drain Current (DC)	I_D		1.5	A
Drain Current (Pulse)	I_{DP}	PW≤10μs, duty cycle≤1%	6	A
Allowable Power Dissipation	P_D	Mounted on a ceramic board (900mm²×0.8mm) 1unit	0.8	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +125	°C
[SBD]				
Repetitive Peak Reverse Voltage	V_{RRM}		15	V
Non-repetitive Peak Reverse Surge Voltage	V_{RSM}		15	V
Average Output Current	I_O		1	A
Surge Forward Current	I_{FSM}	50Hz sine wave, 1 cycle	10	A
Junction Temperature	Tj		-55 to +125	°C
Storage Temperature	Tstg		-55 to +125	°C

Marking : QD

Electrical Characteristics at Ta=25°C

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
[MOSFET]						
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	I_D=1mA, V_{GS}=0	20			V
Zero-Gate Voltage Drain Current	I_{DSS}	V_{DS}=20V, V_{GS}=0			1	μA
Gate-to-Source Leakage Current	I_{GSS}	V_{GS}=±8V, V_{DS}=0			±10	μA
Cutoff Voltage	V_{GS}(off)	V_{DS}=10V, I_D=1mA	0.4		1.3	V
Forward Transfer Admittance	|yfs|	V_{DS}=10V, I_D=1A	1.9	2.8		S
Static Drain-to-Source On-State Resistance	R_{DS}(on)1	I_D=1A, V_{GS}=4V		160	210	mΩ
	R_{DS}(on)2	I_D=0.5A, V_{GS}=2.5V		200	280	mΩ
	R_{DS}(on)3	I_D=0.1A, V_{GS}=1.8V		280	390	mΩ
Input Capacitance	Ciss	V_{DS}=10V, f=1MHz		100		pF
Output Capacitance	Coss	V_{DS}=10V, f=1MHz		22		pF
Reverse Transfer Capacitance	Crss	V_{DS}=10V, f=1MHz		15		pF
Turn-ON Delay Time	t_d(on)	See specified Test Circuit		6.5		ns
Rise Time	t_r	See specified Test Circuit		28		ns
Turn-OFF Delay Time	t_d(off)	See specified Test Circuit		19		ns
Fall Time	t_f	See specified Test Circuit		13		ns
Total Gate Charge	Qg	V_{DS}=10V, V_{GS}=10V, I_D=1.5A		4.5		nC
Gate-to-Source Charge	Qgs	V_{DS}=10V, V_{GS}=10V, I_D=1.5A		0.4		nC
Gate-to-Drain “Miller” Charge	Qgd	V_{DS}=10V, V_{GS}=10V, I_D=1.5A		0.4		nC
Diode Forward Voltage	V_{SD}	I_S=1.5A, V_{GS}=0		0.83	1.2	V
[SBD]						
Reverse Voltage	V_R	I_R=1mA	15			V
Forward Voltage	V_F1	I_F=0.5A		0.30	0.35	V
	V_F2	I_F=1A		0.35	0.40	V
Reverse Current	I_R	V_R=6V			500	μA
Interterminal Capacitance	C	V_R=10V, f=1MHz, 1 cycle		42		pF
Reverse Recovery Time	t_{rr}	I_F=I_R=100mA, See specified Test Circuit.			15	ns
Therminal Resistance	Rth(j-a)	Mounted on a ceramic board (900mm²×0.8mm)		110		°C / W

Electrical Connection (Top view)



1 : Cathode
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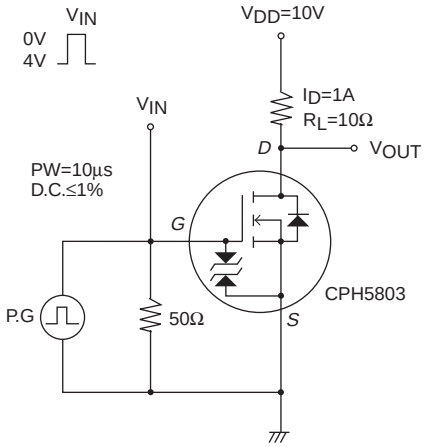
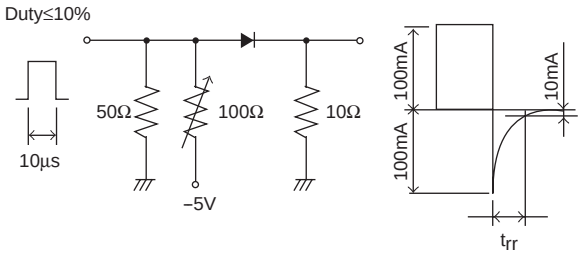
Switching Time Test Circuit

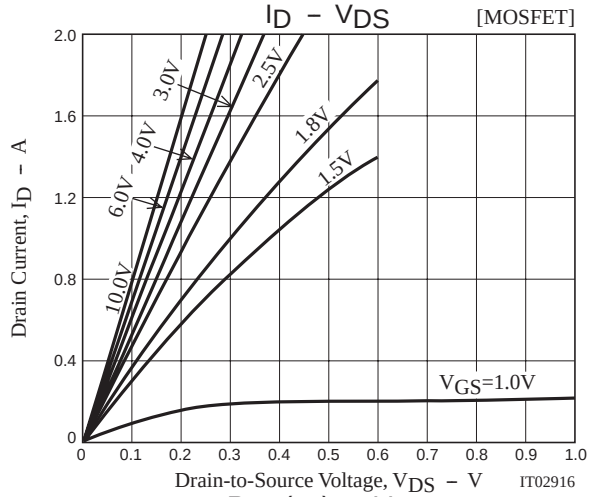
[MOSFET]

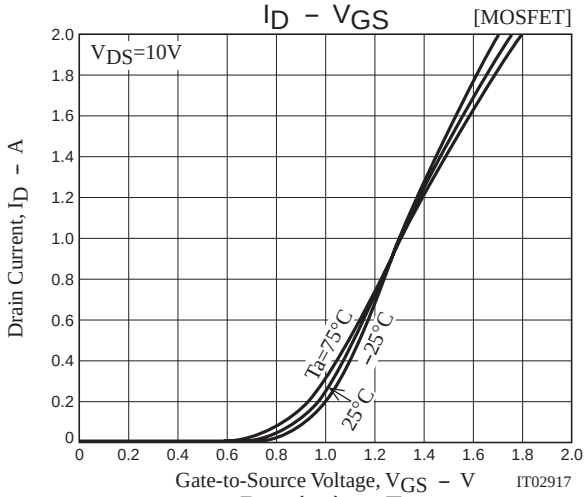


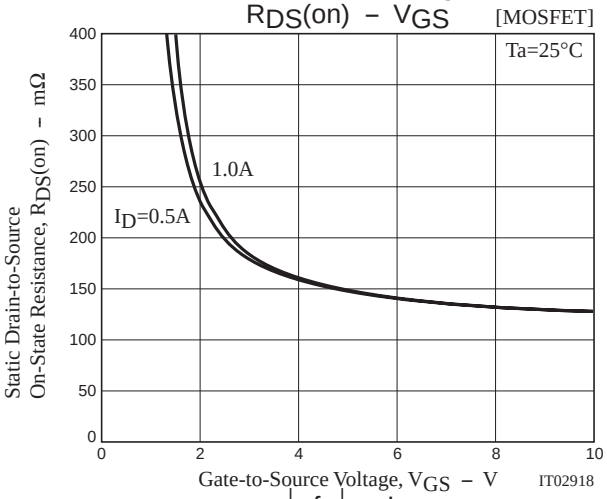
trr Test Circuit

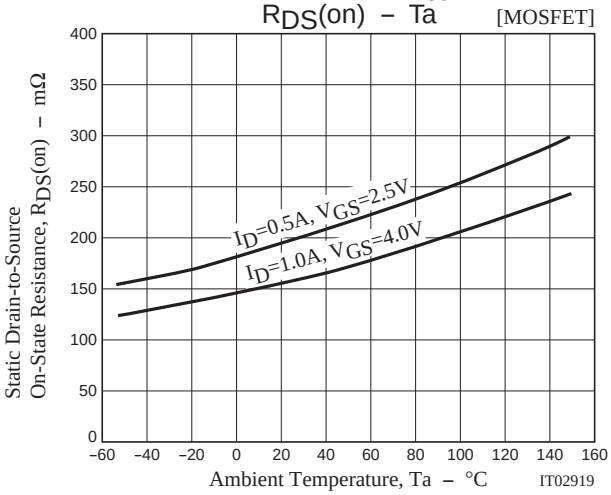
[SBD]

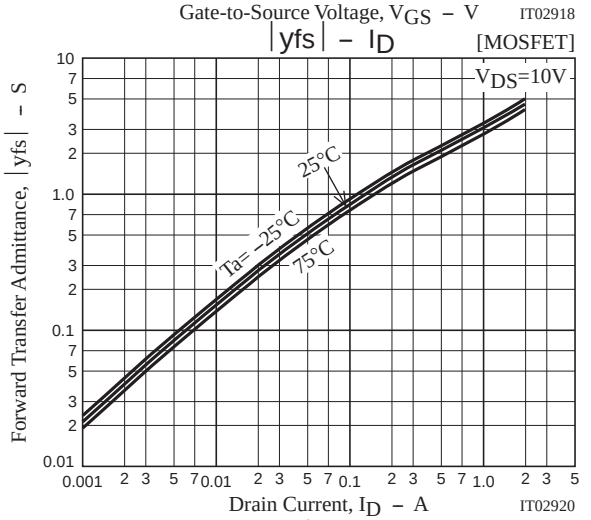


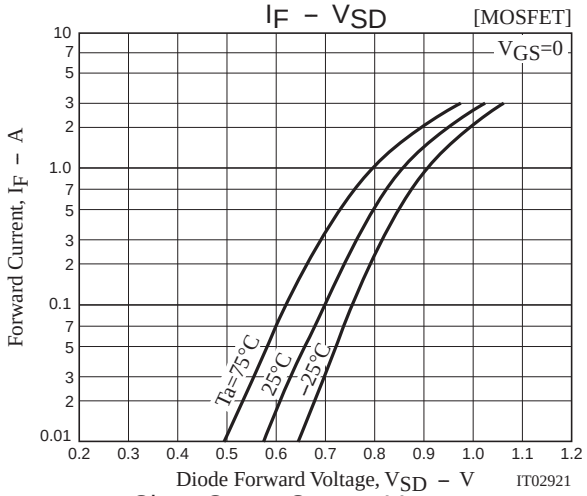

ID – VDS [MOSFET]
Drain Current, ID – A
Drain-to-Source Voltage, VDS – V
IT02916
3.0V
2.5V
1.8V
1.5V
6.0V
4.0V
10.0V
VGS=1.0V

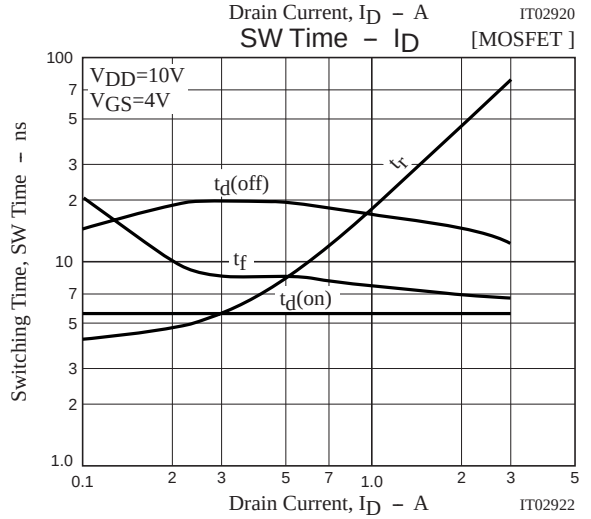

ID – VGS [MOSFET]
VDS=10V
Drain Current, ID – A
Gate-to-Source Voltage, VGS – V
IT02917
Ta=75°C
25°C
–25°C

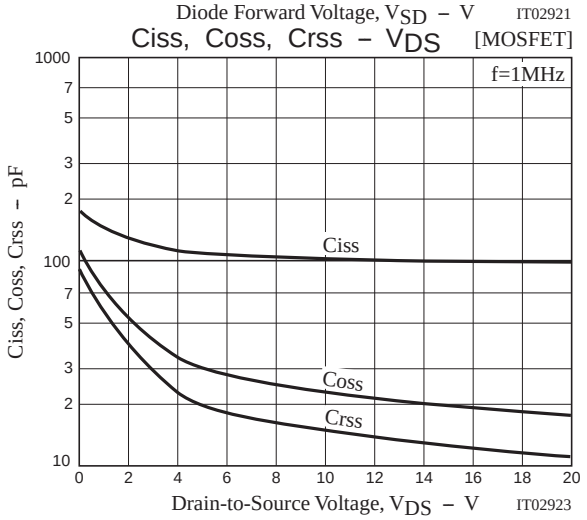

RDS(on) – VGS [MOSFET]
Ta=25°C
Static Drain-to-Source On-State Resistance, RDS(on) – mΩ
Gate-to-Source Voltage, VGS – V
IT02918
1.0A
ID=0.5A

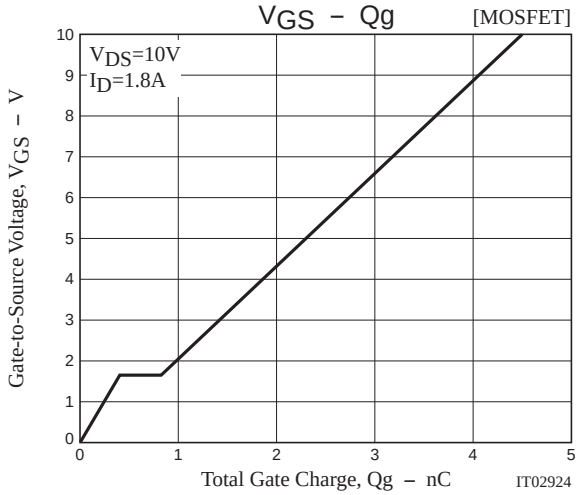

RDS(on) – Ta [MOSFET]
Static Drain-to-Source On-State Resistance, RDS(on) – mΩ
Ambient Temperature, Ta – °C
IT02919
ID=0.5A, VGS=2.5V
ID=1.0A, VGS=4.0V

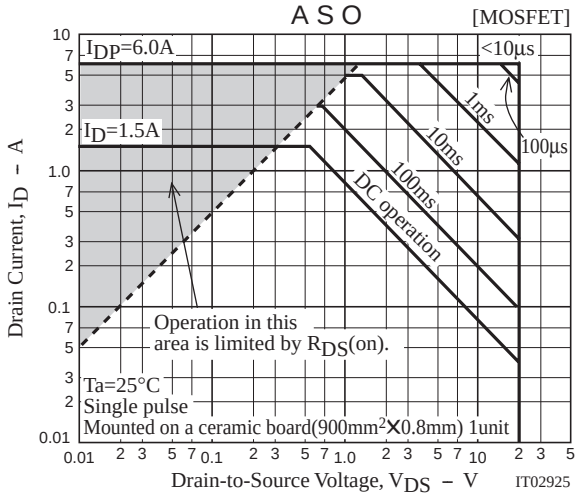

|yfs| – ID [MOSFET]
VDS=10V
Forward Transfer Admittance, |yfs| – S
Drain Current, ID – A
IT02920
25°C
Ta=–25°C
75°C

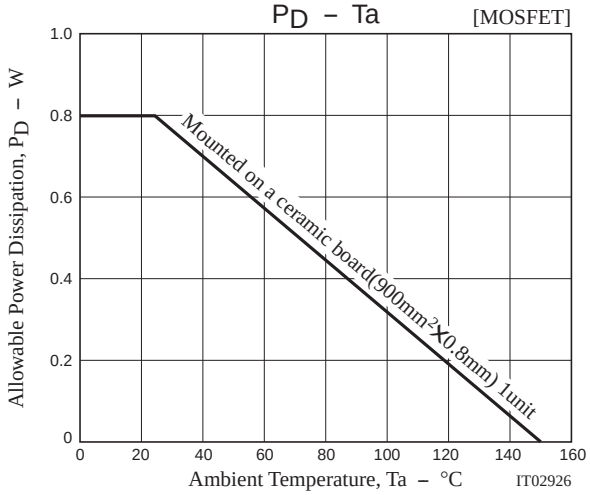

IF – VSD [MOSFET]
VGS=0
Forward Current, IF – A
Diode Forward Voltage, VSD – V
IT02921
Ta=75°C
25°C
–25°C

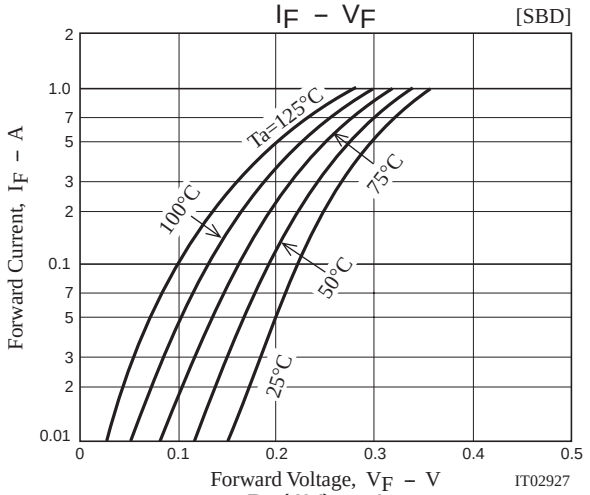

SW Time – ID [MOSFET]
VDD=10V
VGS=4V
Switching Time, SW Time – ns
Drain Current, ID – A
IT02922
td(off)
tf
tr
td(on)

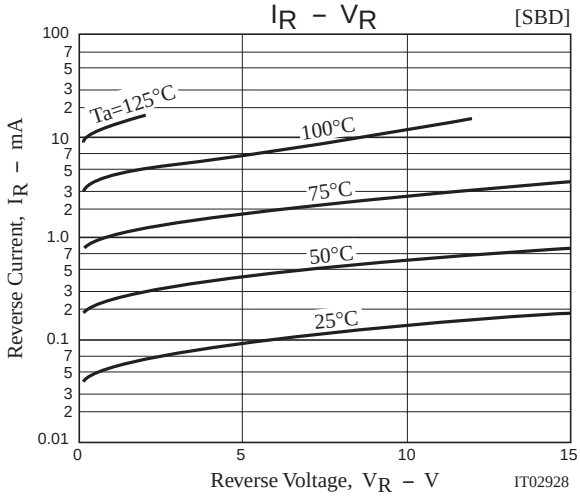

Ciss, Coss, Crss – VDS [MOSFET]
f=1MHz
Ciss, Coss, Crss – pF
Drain-to-Source Voltage, VDS – V
IT02923
Ciss
Coss
Crss

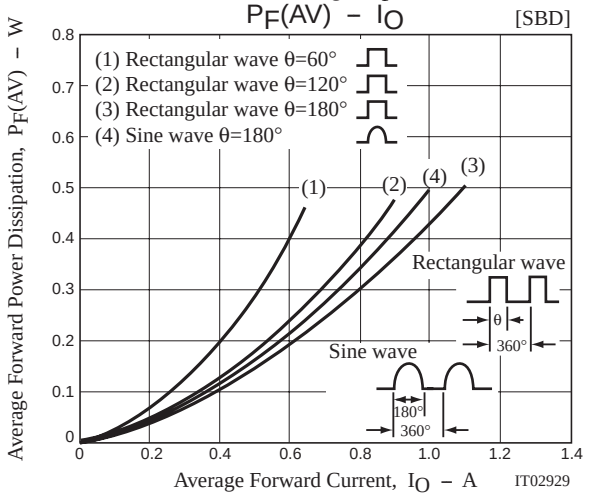

VGS – Qg
[MOSFET]
VDS=10V
ID=1.8A
Gate-to-Source Voltage, VGS – V
Total Gate Charge, Qg – nC
IT02924

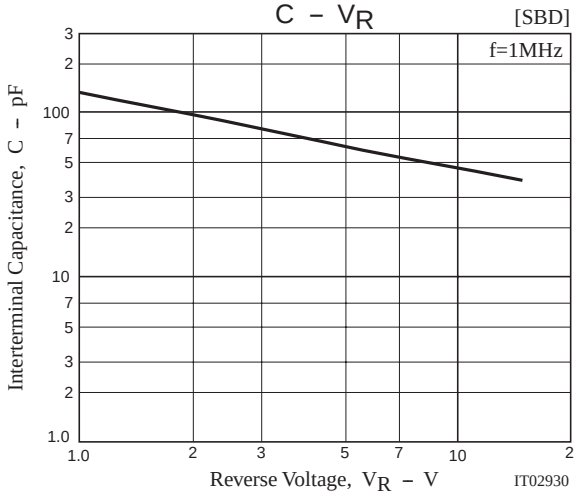

A S O
[MOSFET]
IDP=6.0A
<10μs
ID=1.5A
1ms
10ms
100μs
100ms
DC operation
Operation in this
area is limited by RDS(on).
Ta=25°C
Single pulse
Mounted on a ceramic board(900mm2×0.8mm) 1unit
Drain Current, ID – A
Drain-to-Source Voltage, VDS – V
IT02925


PD – Ta
[MOSFET]
Mounted on a ceramic board(900mm2×0.8mm) 1unit
Allowable Power Dissipation, PD – W
Ambient Temperature, Ta – °C
IT02926


IF – VF
[SBD]
Ta=125°C
100°C
75°C
50°C
25°C
Forward Current, IF – A
Forward Voltage, VF – V
IT02927


IR – VR
[SBD]
Ta=125°C
100°C
75°C
50°C
25°C
Reverse Current, IR – mA
Reverse Voltage, VR – V
IT02928


PF(AV) – IO
[SBD]
(1) Rectangular wave θ=60°
(2) Rectangular wave θ=120°
(3) Rectangular wave θ=180°
(4) Sine wave θ=180°
(1)
(2)
(4)
(3)
Rectangular wave
θ
360°
Sine wave
180°
360°
Average Forward Power Dissipation, PF(AV) – W
Average Forward Current, IO – A
IT02929


C – VR
[SBD]
f=1MHz
Interterminal Capacitance, C – pF
Reverse Voltage, VR – V
IT02930